

**AMENDMENT TO THE CLAIMS:**

Claims 1-23 (Cancelled)

24. (New) A polishing and cleaning compound system comprising:

a polishing device unit operable to polish a thin disc-shaped work piece;

a cleaning device unit arranged in series with said polishing device; and

a transporting mechanism operable to transport the work piece from a container which installs a plurality of the work pieces to said polishing device unit and said cleaning device unit in turn,

wherein said polishing device unit comprises:

a pair of cylindrical polishing tools which are in contact with the work piece linearly at a position with a specific value lower than a horizontal reference line passing through a center point of the work piece with an inclination to the horizontal reference line at a specific angle;

a first holder operable to vertically grip and hold the work piece transported from the container in which the plurality of the work pieces are installed; and

at least two first rollers operable to rotate which are arranged above said cylindrical polishing tools to limit an upper position of the work piece and to make the work piece rotate along its axis and to make the work piece move such that a center of the work piece crosses a contact area of said cylindrical polishing tools;

wherein said pair of said cylindrical polishing tools are rotated so as to pull the work piece toward said first rollers for rotation,

wherein said first rollers are rotated and moved, and

wherein a polishing process is carried out by pouring abrasive toward said pair of cylindrical polishing tools.

25. (New) A polishing and cleaning compound system according to claim 24, wherein movement of said first rollers is an elliptical movement such that a center of the work piece crosses a contact area of said cylindrical polishing tools.

26. (New) A polishing and cleaning compound system according to claim 24, wherein a first cleaning process is carried out by pouring a liquid on said pair of said cylindrical polishing tools following the polishing process.

27. (New) A polishing and cleaning compound system according to claim 25, wherein a first cleaning process is carried out by pouring a liquid on said pair of said cylindrical polishing tools following the polishing process.

28. (New) A polishing and cleaning compound device according to claim 26, wherein the polishing process and the first cleaning process are overlapped for a specific period of time.

29. (New) A polishing and cleaning compound device according to claim 27, wherein the polishing process and the first cleaning process are overlapped for a specific period of time.

30. (New) A polishing and cleaning compound device according to claim 24, wherein said cleaning device unit comprises:

a plurality of second holders, each of which comprises at least three second rollers operable to rotate, wherein said second holders are arranged so as to contact a circumferential edge of the work pieces transported from the polishing device unit so as to hold the work pieces;

a circular transport mechanism in which said second holders are arranged circularly in a vertical direction and which makes the work piece move to a specific position;

cleaning tools which grip the work piece moved to the specific position by said transport mechanism and clean the work piece by rotating; and

a cleaning device which makes the work piece rotate to carry out a cleaning process.

31. (New) A polishing and cleaning compound device according to claim 25, wherein said cleaning device unit comprises:

a plurality of second holders, each of which comprises at least three second rollers operable to rotate, wherein said second holders are arranged so as to contact a circumferential edge of the work pieces transported from the polishing device unit so as to hold the work pieces;

a circular transport mechanism in which said second holders are arranged circularly in a vertical direction and which makes the work piece move to a specific position;

cleaning tools which grip the work piece moved to the specific position by said transport mechanism and clean the work piece by rotating; and

a cleaning device which makes said work piece rotate to carry out a cleaning process.

32. (New) A polishing and cleaning compound device according to claim 26, wherein said cleaning device unit comprises:

a plurality of second holders, each of which comprises at least three second rollers operable to rotate, wherein said second holders are arranged so as to contact a circumferential edge of the work pieces transported from the polishing device unit so as to hold the work pieces;

a circular transport mechanism in which said second holders are arranged circularly in a vertical direction and which makes the work piece move to a specific position;

cleaning tools which grip the work piece moved to the specific position by said transport mechanism and clean the work piece by rotating; and

a cleaning device which makes said work piece rotate to carry out a second cleaning process.

33. (New) A polishing and cleaning compound device according to claim 27, wherein said cleaning device unit comprises:

a plurality of second holders, each of which comprises at least three second rollers operable to rotate, wherein said second holders are arranged so as to contact a circumferential edge of the work pieces transported from the polishing device unit so as to hold the work pieces;

a circular transport mechanism in which said second holders are arranged circularly in a vertical direction and which makes the work piece move to a specific position;

cleaning tools which grip the work piece moved to the specific position by said transport mechanism and clean the work piece by rotating; and

a cleaning device which makes said work piece rotate to carry out a second cleaning process.

34. (New) A polishing and cleaning compound device according to claim 28, wherein said cleaning device unit comprises:

a plurality of second holders, each of which comprises at least three second rollers operable to rotate, wherein said second holders are arranged so as to contact a circumferential edge of the work pieces transported from the polishing device unit so as to hold the work pieces;

a circular transport mechanism in which said second holders are arranged circularly in a vertical direction and which makes the work piece move to a specific position;

cleaning tools which grip the work piece moved to the specific position by said transport mechanism and clean the work piece by rotating; and

a cleaning device which makes said work piece rotate to carry out a second cleaning process.

35. (New) A polishing and cleaning compound device according to claim 29, wherein said cleaning device unit comprises:

a plurality of second holders, each of which comprises at least three second rollers operable to rotate, wherein said second holders are arranged so as to contact a circumferential edge of the work pieces transported from the polishing device unit so as to hold the work pieces;

a circular transport mechanism in which said second holders are arranged circularly in a

vertical direction and which makes the work piece move to a specific position;

cleaning tools which grip the work piece moved to the specific position by said transport mechanism and clean the work piece by rotating; and

a cleaning device which makes said work piece rotate to carry out a second cleaning process.